Characteristics of general inverter VTC: Threshold voltages: $r_d = \frac{1}{k(V_{GS}-V_T)^2\lambda}$ $\mathit{V}_{\!I}L$ - is the maximum allowable input Static Resistance(dc): Q= any voltage such that the gate is off $R_DS = V_{DS}/I_{DS}$ * V_IH -is the min allowable input voltage such MOS inverters (body -source connected) that the gate is on (Note) - Vo is taken across ML(S) and MD(D) * The above threshold voltages are found Resistive E-NMOS inverter by setting dVo/dVi = -1* The Resistor (load) is connected to * undefined logic level between : V_{IL} Vdd, this is then connected to the drain <= Vi <= V_{IH} of the E-NMOS (driver) * V_{OH} = output when vi=0 * It takes up to much space * V_{OL} = output when vi=VoH Saturated Enhancement load E-NMOS $V_{tw} = V_{IH} - V_{IL}$ * The E-NMOS (ML) its drain con.to * A good logic gate has a small Vdd, its gate connected V_{GL} to V_{SL}, transition width this is then connected to the drain $V_{ls} = V_{OH} - V_{OL}$ of the E-NMOS (M D), Vi = V GD* A good logic gate has a large logic * lower Voh, lower NM, small V_{ls} swina large V_{tw}, decr exp graph Noise Margin: ability of a digital logic Linear Enhancement Load circuit to maintain its logic state * two batteries under varying voltage levels Depletion load NMOS inverter Noise Margins: * The D-NMOS(ML), its drain->Vdd, $NM_H - V_{OH} - V_{IH}$ ML's gate is connected to its $NM_L - V_{IL} - V_{OL}$ source. That source terminal connected to $NM = minNM_L, NM_H$ drain of driver (MD). Example : VTC of ideal inverter * Only uses one batt. $V_{OH} = V_{CC}$ Example Problems : $V_{OL} = 0$ $k_D(V_i - V_{TD})^2 = k_L[2|V_{TL}|(V_{DD} - V_o) - (V_{DD} - V_o)^2]$ $V_{IH} = V_{IL} = V_{CC}/2$ $K_R = geometric ratio = \frac{k_D}{K_T}$ $NM_H = \frac{V_{DD}}{2}$ Design NOR and NAND - using NMOS inverter (M_L $NM_L = \frac{V_{DD}}{2}$ config like inv) $V_{ls} = V_{DD}$ NAND - $\texttt{M}_{\{D1\}}$.. $\texttt{M}_{\{Dn\}}$ in series $V_{tw} = 0$ * drivers are the same trans $\frac{Vo}{Vi}|_{V_{OL} and V_{OH}} = \infty$ NOR - M {D1} ..M {Dn} in parallel * driver are the same trans Propagation Delays: CMOS inverter $t_p = \frac{t_{PHL} + t_{PLH}}{2}$ = Max pulse rate for $\star I_{D,max} = I_D(Vi = Vo)$ transmission thru it $V_M = V_i = \frac{V_{TN} + \sqrt{K_R(V_{DD} - |V_{TP}|)}}{1 + \sqrt{K_R}}$ t_{PHL} = time at 50% output Vo falling - time at 50% input rising Vi Symmetrical CMOS inverters t_{PLH} = time at 50% output Vo rising - time at $\star \quad V_{TN} = |V_{TP}|, k_p = k_N, Coxsame, V_M = V_{DD}/2$ 50% input falling Vi $_{\star}$ => $K_{R}=k_{p}/k_{N}=1$ => $\frac{\mu_{N}}{\mu_{p}}=\frac{(W/L)_{p}}{(W/L)_{N}}$ t_r = rise time (10%-> 90%)*Vo (just look at output) * Usually $\mu p = 2.5 = (W/L) p =$ t_f = fall time (90% -> 10%)*Vo (just look at 2.5* (W/L) _L_p $(W/L)_p = 2.5* (W/L)_{Lp \text{ W/L}}$ _p = output) 2.5* (W/L)_L_p $W/L)_p = 2.5* (W/L)_{Lp L}$ p = $CircuitBandwidth = \frac{.35}{t}$ 2.5*(W/L)_L_p $L)_p = 2.5*(W/L)_{Lp}$ p = Diode: $2.5*(W/L)_{Lp} = 2.5*(W/L)_{Lp} = 2.5*(W/L)_{Lp}$ $I_D = I_s(e^{V_D/(\eta * V_T)} - 1$ \$\$ = 2.5*(W/L)_L_p \$\$\$\$ 2.5*(W/L)_L_p Models of diode: $2.5*(W/L)_{Lp} \cdot 5*(W/L)_{_L_p} \cdot .5*(W/L)_{Lp} \star (W/L)_{_L_p}$ (1) ideal switch diode model $*(W/L)_{L_p \text{ W}/\text{L})} \text{_L_p} \text{ } W/L)_{L_p \text{L})} \text{_L_p} \text{ } L)_{L_p} \text{_L_p} \text{_L_p} \text{_p}$ (2) ideal switch with voltage offset p \$ * we use this on in this course (3) piecewise linear Design NOR and NAND - using CMOS inverter \star $I_{off} <= .01I_{on}$ Two input NOR gate (2 Mps and 2 MNs) $\star \quad V_{off} = .6V, V_{on} = .7V$ * M p's connected in series(top near Limitation of Diode digital Circuits V_DD, (G_N) M_N's * Can't implement, NOT, NOR or NAND gates connected in parallel, M_p1 and M_N1 * They have problems, voltage drop across source and drain connected them Gates of M_p1 and M_N1 are connected, N_N2 and M_p2 gates are connected. Enhancement MOS - channel isn't already built Output taken across M_p1 and M_n1 in (normally off) * $1/G_p = 1/g + 1/g => g = 2G_p$ Depletion MOS - channel is already present * $(W/L)_{p,tot} = 2(W/L)_p$ (normally on) * $(W/L)_{N,tot} = (W/L)_N$ Triode section : $V_{GS} > V_{T} and V_{DS} <= V_{GS} - V_{T}$ $I_{DS} = k[2(V_{GS} - V_T)V_{DS} - V_{DS}^2]$ Two input NAND gate (2 Mps and 2 MNs) Saturation region -* M N's connected in series near GND. $V_{GS} > V_{T} and V_{DS} > = V_{GS} - V_{T} \label{eq:VGS}$ Output is taken across the intersection $I_{DS} = k(V_{GS} - V_T)^2$ of M_N1 and M_P1, M_P1 and M_P2 are $k = (1/2) \mu_N C_{ox} * (W/L) \quad \text{[A/V^2]}$ connected in parallel, gates are k = (1/2)k'(W/L)from each M_Ni to M_pi like inverter. Body Effect * $1/G_N = 1/g + 1/g => g = 2G_N$ $V_T = V_{T0} + \gamma * (\sqrt{2|\phi_F|} * V_{SB} - \sqrt{2|\phi_F|})$ $\star \quad (W/L)_{N,tot} = 2(W/L)_N$ PMOS - like NMOS but S(VDD) and D(GND) * $(W/L)_{p,tot} = (W/L)_p$ Triode section : $V_{SG} > |V_T| and V_{SD} <= V_{SG} - |V_T|$

* $I_{SD} = k[2(V_{SG} - |V_T|)V_{SD} - V_{SD}^2]$

Saturation region :

MOS Equiv circuits:

 $g_m = \frac{\Delta I_D}{\Delta V_{GS}}|_{\Delta V_{DS}=0}$ $=> g_m = 2k * (V_{GS} - V_T)$ $=> g_m = 2\sqrt{kI_D}$

 $V_{SG} > |V_T| and V_{SD} > = V_{SG} - |V_T|$ $I_{SD} = k(V_{SG} - |V_T|)^2$

Transconductance: Q = saturation

Dynamic Resistance(ac): Q = Saturation

CMOS VTC Regions

 $0 \le V_i \le V_{TN}$ $V_{TN} \le V_i \le V_M$ V_M $V_M < V_i < V_{DD} - |V_{TP}|$ < VOhmic off ohmic sat

EE 307 Solved Examples 1: Design of NMOS and CMOS Gates Gate designs are based on good inverter designs.

1. For a depletion unos inverter and a depletion NOTE: Improve NMOS conserted and a depletion NMOS 4-input NAND gate with equal logic leads, $K_D'=45\mu R/V^3$, $K_L=40\mu R/V^3$, $V_{TNO}=1.5V_1$, $V_{TDO}=-3V$. First the insenter, $(\frac{V_L}{V_D})_0=2$. The body effect is to be ignored and $V_{0L}=0.25V_1$ for both justs when $V_{DD}=5V$.

(a) Complete the design of the invertex by finding its (2).

(b) Complete the design of the x-injust nomes name gate by finding its (2) b & (2).

 $\frac{1}{100} = \frac{1}{100} \left[\frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \sqrt{100} \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \left(\frac{1}{100} \right) \right] + \frac{1}{100} \left[\frac{1}{100} \left(\frac{1}{100} \right) \left(\frac{$ Is = 1.6875 kb

For Load, VDSL = VDO-VOL = 4.75U > (VGSL-VTL) = (0-(-3)) - Setur- $\begin{aligned}
I_{DL} &= \frac{1}{2} K_{L} \left(\frac{1}{2} \right)_{L} \left[0 - \left(\frac{1}{2} \right)_{L}^{2} \right] = 4.5 K_{L} \left(\frac{1}{2} \right)_{L} \\
I_{DD} &= I_{DL} \implies 1.6875 K_{D} = 4.5 K_{L} \left(\frac{1}{2} \right)_{L} \\
\left(\frac{1}{2} \right)_{L} &= 0.422
\end{aligned}$ aav 9 4m

Load for invester and MAND

A -1

are identical - (42) = 0.422 a) in Load (1)(2) b increases proportionately with computer (1) = 4x(2) for white

CMOS GATE DESIGN

Example 2: For a symmatrical cross invertex and a symmatrical 3-(next cross now gate with a 5 µM process, 40 = 25 and (2) n 2 20 m for the inverter

a Find Wp & Lp for the PMOS tomestor in the investee is Sketch the 3-input cmos was gote and find wind Lin for its name transistors a Find was to for the PMOS transistors in the 3-input more gote.

(a)
$$\frac{S_{o} \mid ultimer}{For the invertex}$$
, $\left(\frac{\omega}{L}\right)_{p} = \frac{\mu_{m}}{\mu_{p}}\left(\frac{\omega}{L}\right)_{p} = 2.5\left(\frac{20\mu_{m}}{5\mu_{m}}\right)$

$$\left(\frac{\omega}{L}\right)_{p} = \frac{50MM}{5\mu_{m}} \Rightarrow \frac{\left[\omega_{p} = 50\mu_{m}\right]_{L}}{\left[\omega_{p} = 50\mu_{m}\right]_{L}}$$

(w), is same for (invertex & each HMOS in the HOR gate $(\underline{\omega})_{H} = \frac{20\mu M}{5\mu M}$ WN = 204M, LH = 54M

Example 3: CONOS NOR & MAND CHANNEL Areas on a Chip Example 3. CAIS NOR & MAND CHANNER Areas ON a Chap
For a expensable of CMOS (meetles with a SLEAR process,
same = 25, (12) N = 2000.

Left = 25, (12) N = 2000.

Left = 20

(A) Schrient CMOS NDR: Extend sketch of 3-imput CMOS NOR of example 2 by one more imput. (ii) Skatch of 4-imput cmos MAND

(b) PMOS & NMOS Areas on chip for inverter THE = 2.5; (W) = 20 LIM (given) (W) = 2.5 (20MM) = 50MM = 5MM AN = 20×5µm² = 100µM Ap = 50×5µm² = 250µm²

(c) PMOS & HMOS areas on chip for 4- juput cmos NOR

GH, gate = GH, inverter = (W)H, gate = (W), inverter 5um Gp, gate = 4 (ap, noverter = 10(1)p, gate = 4(50) = 200, um An = 20×5 MM2 = 100 MM2 AP = 200 K 5 LLM2 = 1000 LLM2

(d) PMOS & ENMOS AMORES on Chip for a ringest CMOS MAND (in, gate = (an, moreter = (a), gate = (a), moreter = (a), gate = (a), moreter = (a), gate = (a), moreter = (a), more Ap = 80x5 = 400 mm2
Ap = 50x5 = 250 mm

& Comparison

Gate type	Aveas in MM2	
Inventor	100	250
4- luput HOR	100	1000
A-Imput MAND	400	250

& Areas of both GMOS NOA of CMOS NAMO increase with four-in (400 (imputs)), but areas increase out for MOR. Thus NAMO is preferred in CMOS; HAMD is standard gate in CMOS.

